

Description

The VST23N130 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

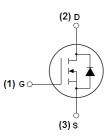
General Features

- $V_{DS} = 230V, I_{D} = 90A$ $R_{DS(ON)} < 15.5 m\Omega @ V_{GS} = 10V$
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST23N130-TC	VST23N130	TO-220C	-	-	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	230	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	90	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	63.6	Α
Pulsed Drain Current	I _{DM}	360	Α
Maximum Power Dissipation	P _D	300	W
Derating factor		2	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	1216	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 175	$^{\circ}$





Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	Rejc	0.5	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Off Characteristics			Min	Тур	Max	Unit
On Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	230		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =230V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	$V_{GS}=\pm20V, V_{DS}=0V$	-	-	±100	nA
On Characteristics (Note 3)						•
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5		4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =45A	-	13	15.5	mΩ
Forward Transconductance	G FS	V _{DS} =10V,I _D =45A	70	-	-	S
Dynamic Characteristics (Note4)						•
Input Capacitance	C _{lss}	., ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	-	4200	-	PF
Output Capacitance	C _{oss}	V_{DS} =100V, V_{GS} =0V, F=1.0MHz	-	333.1	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	8.8	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V_{DD} =100V, I_{D} =45A V_{GS} =10V, R_{G} =4.7 Ω	-	18	-	nS
Turn-on Rise Time	t _r		-	26	-	nS
Turn-Off Delay Time	t _{d(off)}		-	41	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg	\/ 400\/ 450	-	63.2		nC
Gate-Source Charge	Q _{gs}	$V_{DS}=100V, I_{D}=45A,$	-	24		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	16.4		nC
Drain-Source Diode Characteristics						•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =90A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	90	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C$, $I_F = 45$	-	140		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	600		nC

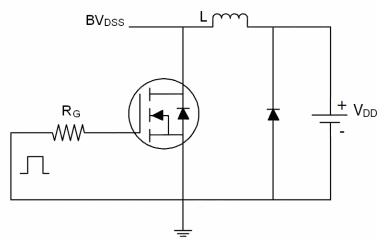
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t \leq 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

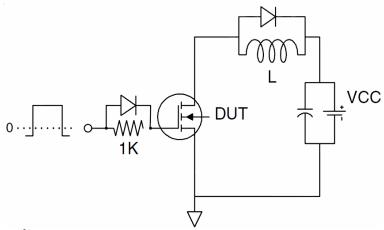


Test Circuit

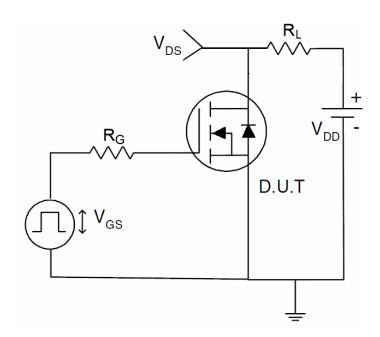
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







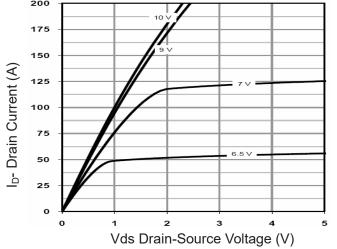


Figure 1 Output Characteristics

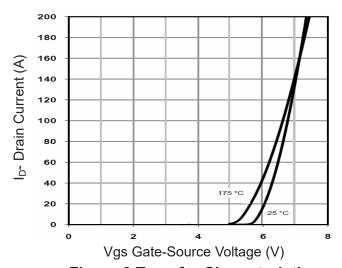
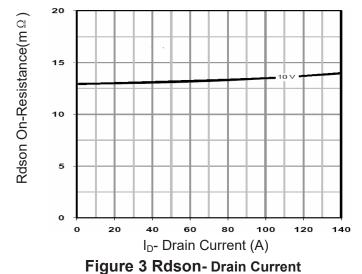


Figure 2 Transfer Characteristics



2.5
V_{GS}=10 V
I_D=45 A

1.5
1.0
1.0
0.5

Figure 4 Rdson-JunctionTemperature

T_J-Junction Temperature(°C)

100

125

150

0.0

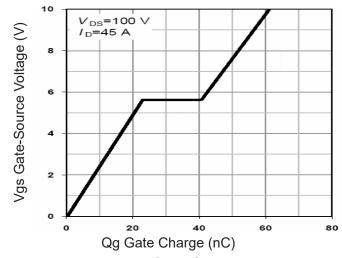


Figure 5 Gate Charge

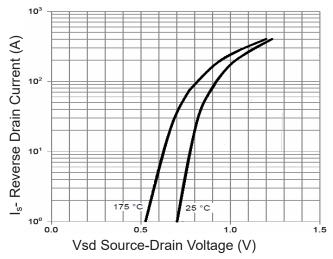
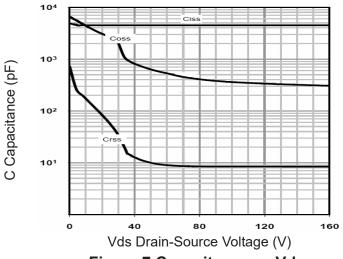


Figure 6 Source- Drain Diode Forward





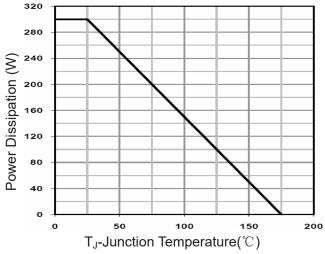
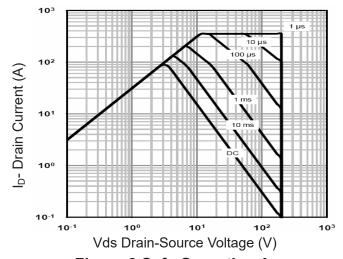


Figure 7 Capacitance vs Vds Figure 9 Power De-rating



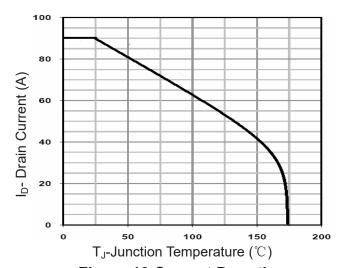


Figure 8 Safe Operation Area

Figure 10 Current De-rating

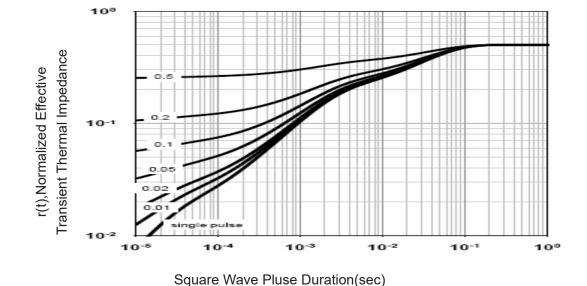


Figure 11 Normalized Maximum Transient Thermal Impedance